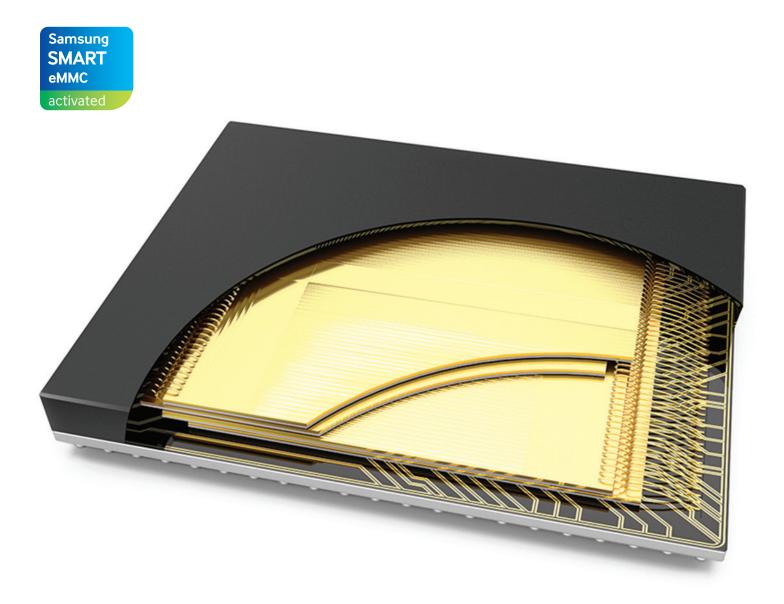
Samsung eMMC

Managed NAND Flash memory solution supports mobile applications



FBGA QDP Package



BROCHURE

Expand device development with capable memory solutions

To meet current trends for advanced mobile device designs, manufacturers require memory that is increasingly dense, robust and small:

- **Dense.** Sophisticated mobile devices require high-density content storage that supports high-definition video play-back and other high-end multimedia features. As a result, memory densities are rapidly advancing.
- **Robust.** Today's fastest and most demanding embedded uses require strong memory management solutions. Embedded uses include multifunctional smartphones, portable media players and tablet computers.
- **Small.** The Joint Electron Device Engineering Council (JEDEC) encourages memory to be produced in extremely compact sizes to allow space for other components.

To focus on these demands, developers need an efficient way to control software development by simplifying mass storage designs and improving device production. Developers also require the ability to create efficient mobile device designs with minimal costs and brief time to market. Finally, they need superior storage capabilities to augment device production.

Samsung has a wide range of eMMC solutions based on performance requirements.

Samsung embedded multimedia card (eMMC) addresses these needs with advanced embedded NAND Flash. The eMMC helps simplify mass storage designs for the latest consumer electronics. Samsung eMMC is produced in very compact sizes (typically smaller than a postage stamp) to create room within devices for additional parts. Key applications that can benefit from Samsung eMMC include advanced mobile devices and handsets. These products use eMMC to expand computing power and content storage. They also use eMMC to provide booting functionality.

Simplify mass storage designs

Conventional NAND Flash memory can be challenging to adopt. Developers may have some difficulty controlling software development, particularly when implementing wear leveling, bad block management, device mapping and error handling. Developers may also encounter issues related to die shrinkage, including page size and error correcting code (ECC) management.

Conversely, Samsung eMMC is designed to be easy to adopt. It is suitable for the latest consumer electronics, including tablets, smartphones, GPS systems and e-readers. Chipset validation means that eMMC is a thoroughly tested solution. Samsung eMMC incorporates a mature interface standardized by JEDEC, and key functionality yields strong power management and performance optimization.

Samsung eMMC provides enhanced storage capabilities, a reduced controller footprint and streamlined data reads and writes. Standardized packaging and device specifications plus intelligent firmware ease design work and provide a common footprint for the use of embedded and removable NAND. Samsung offers a single footprint combining boot, embedded storage and external mass storage in one device.

In addition, Samsung offers a wide range of eMMC solutions based on low (4GB or 8GB) to high (16GB, 32GB, 64GB or 128GB) density requirements.

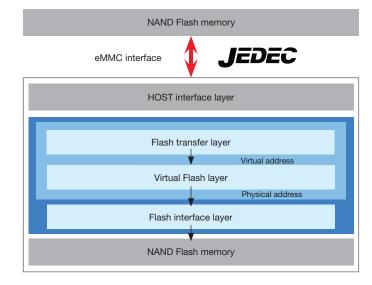


Figure 1. MMC user



Reduce development time and control costs

In the past, a product using NAND memory required changes in the chipset or the OS. At times, the NAND memory also required changes to be made in the Flash translation layer (FTL). The changes then needed to be tested at the NAND level, which could lead to significant delays in product-level testing. In contrast, developers using Samsung eMMC can move directly from product concept to product testing. Samsung eMMC isolates the host from changes in NAND memory technology and bypasses the FTL, which reduces design, development and testing time, and helps control costs.

Samsung eMMC simplifies system design and integration of 2-bit and 3-bit multi-level cell (MLC)-type NAND memory, and triple-level cell (TLC) memory, leading to faster overall time to market. This approach makes Samsung eMMC memory an excellent choice for deployment across a variety of segments, including low-cost legacy chipsets. Samsung eMMC operates at standard 4.41, 4.5, and 5.0 voltage levels, so there is no need to develop or use separate firmware. This interface turns memory accesses into straightforward read-write operations with advanced security and reliability features.

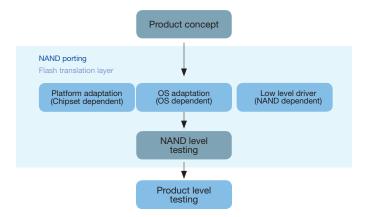


Figure 2. Samsung eMMC memory enables users to proceed from product concept directly to product testing.

Increase storage capabilities for diverse applications

Advanced mobile devices and handsets can use Samsung eMMC to expand computing power and content storage. Enhanced storage solutions for mobile devices that provide high-density solid state memory can be integrated into system designs. Traditional storage media, as a result of the high storage capacity of eMMC, can be replaced by lower-power solid-state drives (SSDs). Including SSDs enables increased storage densities, reduced costs and low power consumption. Content storage supports high-definition video playback and other complex multimedia features. Computing power provides booting functionality.

Samsung eMMC comprises high-density 2-bit and 3-bit MLC NAND, and an intelligent MMC controller in a Ball Grid Array (BGA) package.

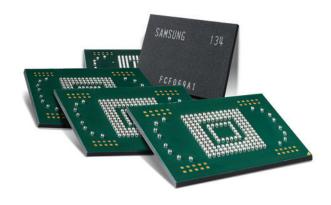


Figure 3. 10nm-class eMMC

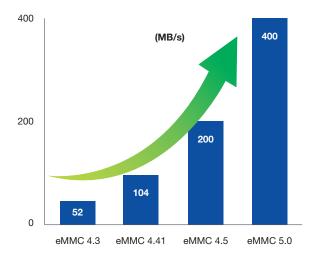


Create an efficient way to develop well-designed mobile devices

To maintain the required data rates and throughput for high-density chips, the eMMC standard was developed to enhance storage capabilities, reduce controller footprint and streamline data reads and writes. Advanced Samsung technology helps reduce the cost of application development and increase work efficiency, enabling developers to stay competitive by building better and faster.

Samsung eMMC contributes to successful mobile device development. The intelligent interface is designed for ease of use, and enhanced storage solutions improve device designs. Samsung eMMC also helps developers go straight from concept to testing, reducing time to market.

eMMC Interface Bandwidth



| Features | Benefits |
|---|--|
| Density of 4 GB to 128 GB | Contributes to a variety of mobile & consumer designs |
| Small size | Helps meet today's mobile design requirements Frees up space for other components |
| Enhanced storage capabilities | Enhances robust mobile devices Enables traditional storage media to be replaced by lower-power SSDs |
| Advanced embedded NAND Flash | Helps simplify mass storage designs Aids in expanding computing power and content storage Is designed for easier adoption |
| Standard, mature interface by JEDEC | Provides strong power management and performance optimization Open, Standard Specifications for device features, function, and package pinout |
| Intelligent firmware | Facilitates easier design work Provides a common footprint for the use of embedded and removable NAND |
| Single footprint | Combines boot, embedded storage and external mass storage in one device |
| Isolation of the host from changes in NAND memory technology | Enables developers to move directly from product concept to product testing |
| FTL bypass | Reduces design, development and testing time |
| Mobile-Centric | Optimized for very low power consumption |

Features and benefits



| eMMC Features | eMMC 4.5 | eMMC 5.0 |
|--|-----------------|------------------|
| Interface Speed/Max Bandwidth | 200MB/s | 400MB/s |
| Clock Frequency | 200MHz | 200MHz |
| Data Rate, Mode | HS200, SDR | HS400, DDR |
| Bus Width | x4/x8 | x4/x8 |
| H/W Reset | Yes | Yes |
| Multi-Partition | Yes | Yes |
| Enhanced Mode (SLC + MLC) | Yes | Yes |
| Alternative Boot | Yes | Yes |
| Security Features (Trim, RPMB, Secure Erase, Secure Trim) | Yes | Yes |
| Secure Trim Refinement | Yes | Yes |
| High Priority Interrupt | Yes | Yes |
| Back Ground Operation | Yes | Yes |
| Packed Command | Yes | Yes |
| Cache Handling | Yes | Yes |
| Discard | Yes | Yes |
| Dynamic Capacity | Yes | Yes |
| Sanitize | Yes | Yes |
| Smart Report | Vendor Specific | Yes-standardized |
| F/W Update | N/A | Yes-standardized |

Samsung eMMC Part Number Matrix

Standard eMMC:

| Density | Part Number | Flash | ммс | Class* | Seq R/W (MB/s) | Ran R/W IOPS | Pkg Size (mm) | Status |
|---------|-----------------|--------|-----|--------|----------------|--------------|---------------|--------|
| 4 GB | KLM4G1YEMD-C031 | 32Gb*1 | | 200 | 100/6 | 2500/200 | 11.5x13x0.8 | CS |
| 8 GB | KLM8G1WEMB-B031 | 64Gb*1 | | 200 | 100/6 | 2500/200 | 11.5x13x0.8 | CS |
| 16 GB | KLMAG2WEMB-B031 | 64Gb*2 | 5.0 | 700 | 170/11 | 4000/500 | 11.5x13x0.8 | CS |
| 32 GB | KLMBG4WEMC-B031 | 64Gb*4 | | 1500 | 200/50 | 4000/1500 | 11.5x13x1.0 | CS |
| 64 GB | KLMCG8WEMC-B031 | 64Gb*8 | | 1500 | 200/50 | 4000/1500 | 11.5x13x1.0 | CS |

High-Performance eMMC-Pro:

| Density | Part Number | Flash | ммс | Class* | Seq R/W (MB/s) | Ran R/W IOPS | Pkg Size (mm) | Status |
|---------|-----------------|---------|-----|--------|----------------|--------------|---------------|--------|
| 4 GB | KLM4G1FEAC-B031 | 32Gb*1 | 5.0 | 700 | 150/10 | 4000/700 | 11x10x0.8 | MP |
| 8 GB | KLM8G1GEAC-B031 | 64Gb*1 | | 700 | 180/20 | 4000/700 | 11.5x13x1.0 | MP |
| 16 GB | KLMAG2GEAC-B031 | 64Gb*2 | | 2000 | 240/40 | 6000/2500 | 11.5x13x1.0 | MP |
| 32 GB | KLMBG4GEAC-B031 | 64Gb*4 | | 2000 | 240/60 | 6000/2500 | 11.5x13x1.0 | MP |
| 64 GB | KLMCG8GEAC-B031 | 64Gb*8 | | 2000 | 240/60 | 6000/2500 | 11.5x13x1.2 | MP |
| 128 GB | KLMDGAGEAC-B001 | 64Gb*16 | 4.5 | 2000 | 150/50 | 3500/2000 | 11.5x13x1.4 | MP |

* eMMC Class refers to RW IOPS

** eMMC Performance Conditions: Bus width x8, cache on, 512KB data transfer, device is full w/o file system overhead

*** eMMC 5.0 is JEDEC Compliant and is backwards compatible with older eMMC versions such as 4.41 & 4.5.



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For more information

For more information about Samsung eMMC, visit www.samsung.com/semiconductor.



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Samsung Electronics Co., Ltd. Giheung Campus, 95, Samsung 2-ro, Giheung-Gu, Yongin, Gyeonggi-Do Korea

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